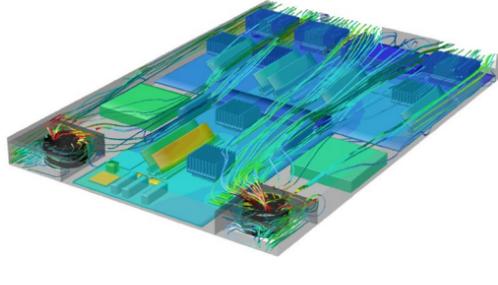


## ANSYS ICEPAK Seminar

ICEPAK technologies, UTAC industry sharing and what's new in ANSYS ICEPAK 14.5



### ANSYS ICEPAK Seminar

Date: 23rd Nov 2012 (Fri)

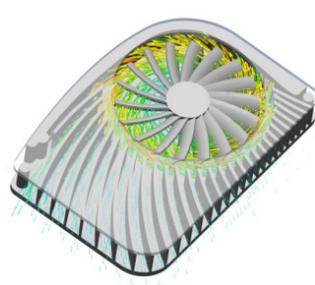
Time: 2pm - 5pm

Place: CAD-IT Office (Singapore)  
(See map below)

**Sign Up Now**

### Agenda

- ANSYS ICEPAK technologies
- Industry sharing session:  
**Mr Gan Kian Yeow\* (Senior R&D Engineer)**  
**United Test and Assembly Center Ltd (UTAC)**
- What's new with ANSYS ICEPAK 14.5
- Question and answer
- Networking

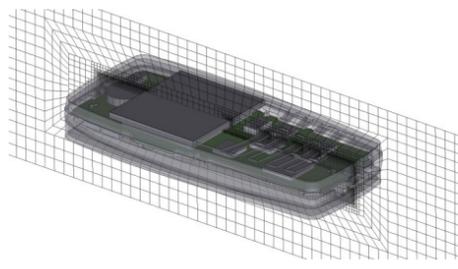


For more information, please contact:

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Hundreds of devices we use every day depend on technologically advanced electromagnetic equipment. Management of high local heat flux is critical to optimizing the performance of these complex designs.

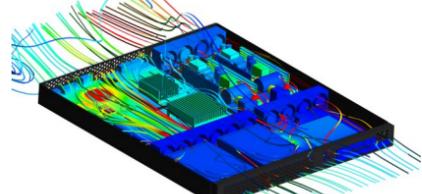


ANSYS ICEPAK is a fully interactive, object-based thermal management and optimization solution for electronic systems and components at every phase of the development cycle.

Built upon the world's leading and industry-proven FLUENT solver and ICFM CFD meshing technology, ICEPAK delivers more speed, more complex problem-solving with robustness and more computational efficiency than any other thermal modeling software.

ANSYS ICEPAK gives unprecedented accuracy in thermal analysis with:

- Advanced hexa-unstructured meshing technology, allowing meshing of curves, inclined objects and non-rectangular components needed to build **high-quality realistic models** for today's complex designs
- Second-order scheme which produces **more accurate temperature gradients** compared to first order schemes normally used
- Ability to take into account the joule-heating effects of **traces and vias** which are normally ignored



ANSYS ICEPAK gives much faster results through:

- Easy to use, powerful and highly automated **meshing technology**
- **Parallel processing** capability, allowing the most complex designs to be analyzed and convergence reached in the shortest time
- Ability to transfer files to **ANSYS Mechanical** solutions for thermal-stress analysis

### Want to learn more?

Find out how ICEPAK can help you when you join us on Friday (23rd November 2012) and hear how it has helped UTAC\* enhance package performance and yield while reducing costs and time to market.

### \*Speaker bio:



Mr Gan Kian Yeow is currently a Senior RnD Engineer in United Test and Assembly Center (UTAC) and was previously from Unisem. He has more than 8 years of experience in the semiconductor industry and has a wide range of skill sets as an advanced user of various CFD and FEA simulation software.

He has successfully demonstrated his simulation capabilities in several conference publications on the international platform. He is currently fronting various key developments in the IC thermal analysis area, using simulation coupled with experimental measurements to enhance package performance and yield.

As an advanced user of ANSYS Icepak, he has not only used Icepak to provide customized thermal solutions to meet customers stringent requirements, he has also successfully used Icepak to develop a new capability for process reflow simulation validated by actual process data. In next phase, he will be developing cutting edge multi-disciplinary thermal-mechanical simulation capability by coupling both CFD and FEA software.

### About CAD-IT

CAD-IT Consultants, formed in 1991 in Singapore, is a global ISO 9001:2008 certified premier product lifecycle management technology solution provider providing affordable, state-of-the-art world class turnkey solutions covering software, consulting, training, support and maintenance services to meet design, engineering, manufacturing and enterprise management needs.

CAD-IT had received 70 International and National Awards since 1991 in recognition of its professionalism in training, service and support of its customers. CAD-IT Consultants currently has 10 offices spread across Singapore, China, Hong Kong, Malaysia, United Kingdom and Thailand.

Since February 2010, CAD-IT has partnered the Singapore Workforce Development Agency (WDA) to offer Advanced Certificate courses in PLM and Engineering Simulation, under the Workforce Skills Qualifications (WSQ) framework, with the charter to upgrade the technological capabilities of organizations in Singapore so as to enable them to undertake high value-add design, engineering, manufacturing and R&D activities.

### Location Details

CAD-IT Consultants (Asia) Pte Ltd

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#03-05 Amtech Building

Singapore 575625

